### SUBMINIATURE SOLID STATE LAMP

Part Number: KM2520EH/1ID

High Efficiency Red

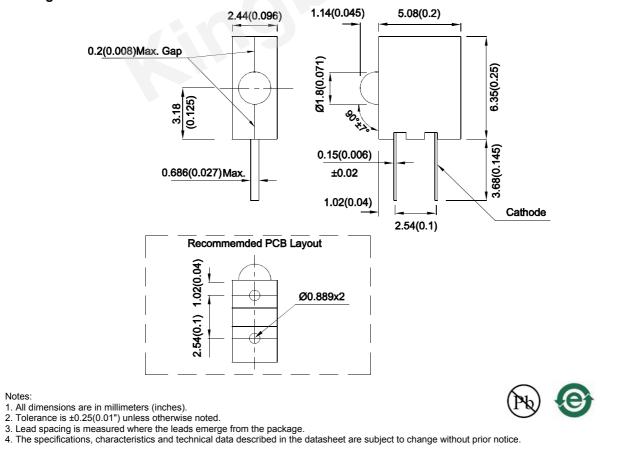
#### Features

- Black case enhances contrast.
- Vibration and shock resistant.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### **Package Dimensions**



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#### Solaction Guida

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KM2520EH/1ID	High Efficiency Red (GaAsP/GaP)	Red Diffused	12	20	20°
		Red Dillused	*8	*16	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity / luminous Flux: +/-15%.
\* Luminous intensity value is traceable to CIE127-2007 standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to CIE127-2007 standards. 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

#### Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	160	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

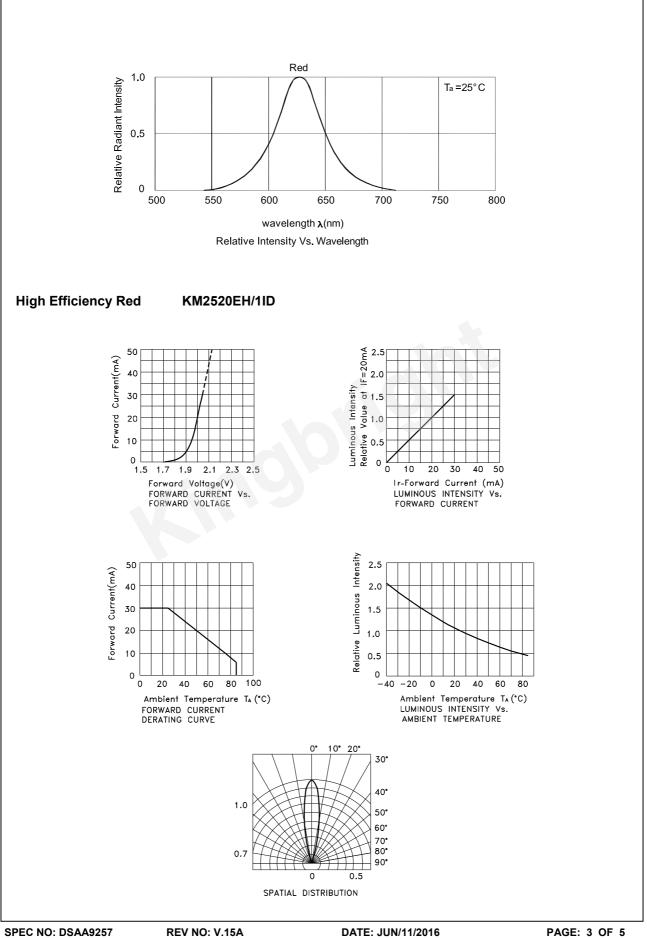
Notes:

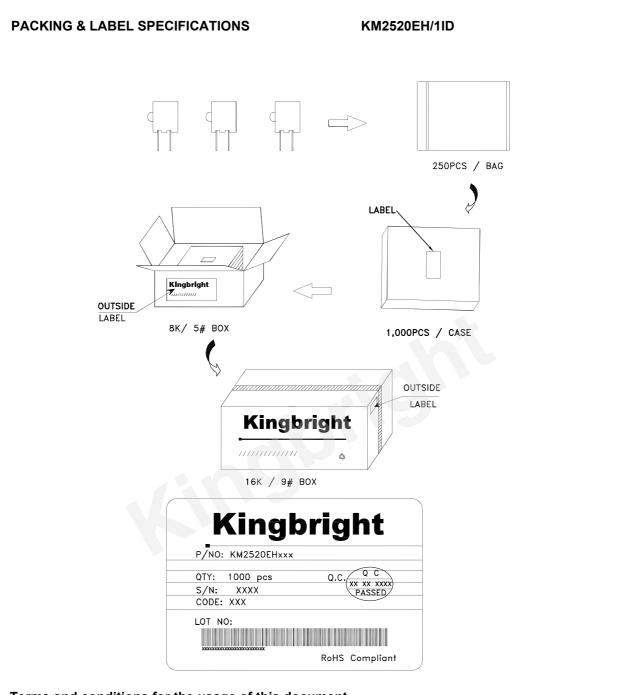
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.

4. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity - Ref JEDEC/JESD625-A and JEDEC/J-STD-033.





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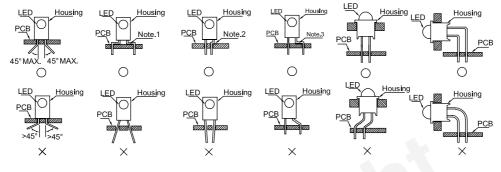
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#### PRECAUTIONS

1. Storage conditions:

a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.

- b.LEDs should be stored with temperature  $\leq$  30°C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



" ( ) " Correct mounting method " imes " Incorrect mounting method

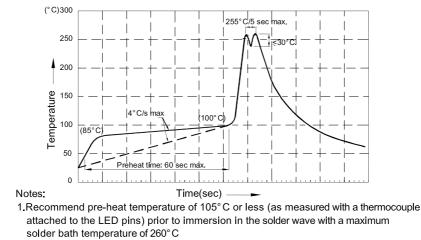
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



4. The tip of the soldering iron should never touch the lens epoxy.

- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4. Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.